

Data sheet acquired from Harris Semiconductor SCHS018C – Revised September 2003

CMOS Dual Complementary Pair Plus Inverter

High-Voltage Types (20-Volt Rating)

■ CD4007UB types are comprised of three n-channel and three p-channel enhancement-type MOS transistors. The transistor elements are accessible through the package terminals to provide a convenient means for constructing the various typical circuits as shown in Fig. 2.

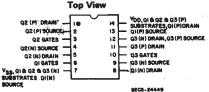
More complex functions are possible using multiple packages. Numbers shown in parentheses indicate terminals that are connected together to form the various configurations listed.

The CD4007UB types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

Applications:

- Extremely high-input impedance amplifiers
- Shapers
- Inverters
- Threshold detector
- Linear amplifiers
- **■** Crystal oscillators

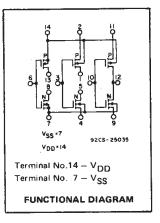
TERMINAL DIAGRAM



CD4007UB Types

Features:

- Standardized symmetrical output characteristics
- Medium Speed Operation tpHL, tpLH = 30 ns (typ.) at 10 V
- 100% tested for quiescent current at 20 V
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"
- Maximum input current of 1 μA at 18 V over full package-temperature range;
 100 nA at 18 V and 25°C



RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	Lif	MITS	UNITS
	MIN.	MAX.	
Supply-Voltage Range			
(For T _A = Full Package Temperature Range)	3	18	v

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER-	CONE	OITION	IS	LIMIT	LIMITS AT INDICATED TEMPERATURES (°C)						
ISTIC	Vo	VIN	VDD					+25			UNITS
	(v)	(V)	(V)	-55	-40	+85	+125	Min.	Тур.	Max.	
Quiescent Dévice	_	0,5	5	0.25	0.25	7.5	7.5	_	0.01	0.25	
Current,		0,10	10	0.5	0.5	15	15		0.01	0,5	μA
IDD Max.	- <u>- </u>	0,15	15	1	1	30	30		0.01	1	μ-
	-	0,20	20	5	5	150	150		0.02	5	
Output Low	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1		
(Sink) Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	34	6.8		
Output High (Source) Current,	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
	2.5	0,5	5	-2	1.8	-1.3	-1.15	-1.6	-3.2		
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6		
IOH Min.	13.5	0,15	15	-4.2	-4	-2.8	2.4	-3.4	-6.8	_	
Output Voltage:	_	0,5	5		0	.05		-	0	0.05	
Low-Level,	_	.0;10	10		0	.05		_	0	0.05	
VOL Max.	_	0,15	15	0.05				-	0	0.05	l v
Output Voltage:	_	0,5	5		4	.95		4.95	5	-]
High-Level,	_	0,10	10		9	.95		9.95	10	_	
VOH Min.	_	0,15	15		14	1.95		14.95	15	<u> </u>	
Input Low	4.5	-	5			1		_	_	1	
Voltage,	9	-	10			2		_		2	
VIL Max.	13.5	-	15			2.5		-		2.5	v
Inpút High Voltage, VIH Min.	0.5	I -	5			4		4	_	_	*
	1	-	10			8		8			
	1.5	T -	15		1	2.5		12.5		_	
Input Current IIN Max.		0,18	18	±0.1	±0.1	±1	±1	-	±10 ⁻⁵	±0.1	μА

CD4007UB Types

MAXIMUM RATINGS, Absolute-Maximum Values:DC SUPPLY-VOLTAGE RANGE, (V_{DD}) -0.5V to +20VVoltages referenced to V_{SS} Terminal)-0.5V to V_{DD} +0.5VINPUT VOLTAGE RANGE, ALL INPUTS-0.5V to V_{DD} +0.5VDC INPUT CURRENT, ANY ONE INPUT $\pm 10mA$ POWER DISSIPATION PER PACKAGE (PD):500mWFor $T_A = -55^{\circ}C$ to $+100^{\circ}C$ 500mWFOR $T_A = +100^{\circ}C$ to $+125^{\circ}C$ Derate Linearity at $12mW/^{\circ}C$ to 200mWDEVICE DISSIPATION PER OUTPUT TRANSISTOR100mWFOR $T_A = FULL$ PACKAGE-TEMPERATURE RANGE (All Package Types)100mWOPERATING-TEMPERATURE RANGE (T_{atg}) $-55^{\circ}C$ to $+125^{\circ}C$ STORAGE TEMPERATURE RANGE (T_{atg}) $-65^{\circ}C$ to $+150^{\circ}C$ LEAD TEMPERATURE (DURING SOLDERING): $+265^{\circ}C$ At distance $1/16 \pm 1/32$ inch $(1.59 \pm 0.79mm)$ from case for 10s max $+265^{\circ}C$

a) Triple Inverters	6 8 3 5 5
(14,2,11); (8,13); (1,5); (7,4,9)	92CS-15350

(13,2); (1,11); (12,5,8); (7,4,9)

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C; Input t_r, t_f = 20 ns, C_L = 50 pF, R_L = 200 K Ω

	COND	ITIONS	LIA			
CHARACTER		V _{DD} Volts	Тур.	Max.	UNITS	
Propagation Delay T		5	55	110		
	tPHL.		10	30	60	ns
	tPLH		15	25	50	1
		1	5	100	200	
Transition Time	THL,		10	50	100	ns
	tТLН		15	40	80	1
Input Capacitance	CIN	Any Input		10	15	pF

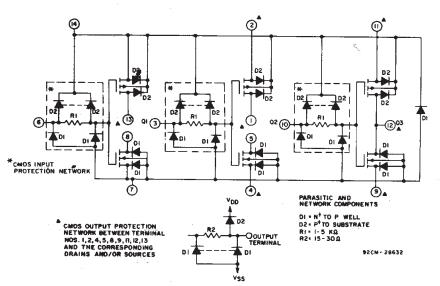


Fig. 1 — Detailed schematic diagram of CD4007UB showing input, output, and parasitic diodes.

c) 3-Input NAND Gate 30 00 12 (1,12,13); (2,14,11); 9205-15348 (4,8); (5,9)

d) Tree (Relay) Logic

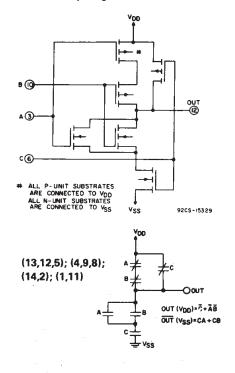
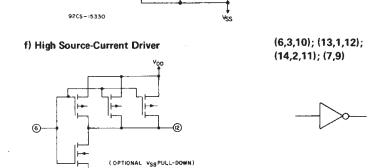


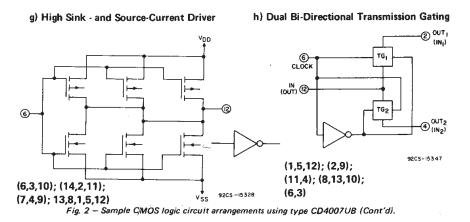
Fig. 2 — Sample C'MOS logic circuit arrangements using type CD4007UB.

CD4007UB Types

e) High Sink-Current Driver (6,3,10); (8.5, 12); (11,14); 7,4,9)



92CS-15327



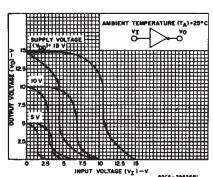


Fig. 6 – Minimum and maximum voltage-transfer characteristics for inverter.

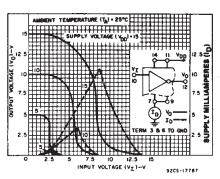


Fig. 7 – Typical current and voltage-transfer characteristics for inverter.

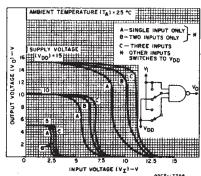


Fig. 3 – Typical voltage-transfer characteristics for NAND gate.

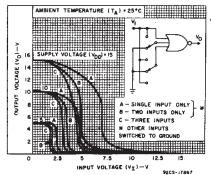


Fig. 4 — Typical voltage-transfer characteristics for NOR gate.

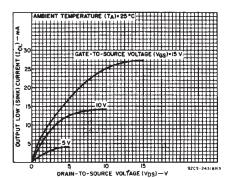


Fig. 5 — Typical output low (sink) current characteristics.

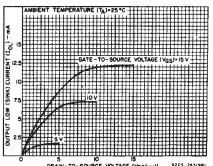


Fig. 8 – Minimum output low (sink)

current characteristics.

CD4007UB Types

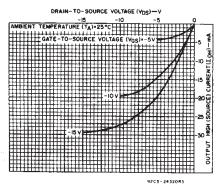


Fig. 9 ~ Typical output high (source) current characteristics.

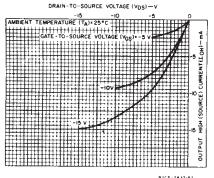


Fig. 10 – Minimum output high (source) current characteristics.

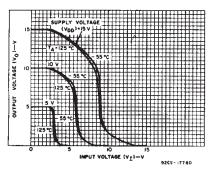


Fig. 11 — Typical voltage-transfer characteristics as a function of temperature.

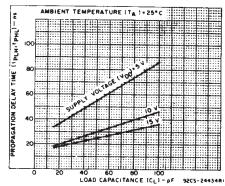


Fig. 12 — Typical propagation delay time vs. load capacitance.

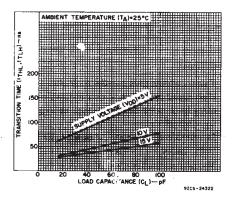


Fig. 13 — Typical transition time vs. load capacitance.

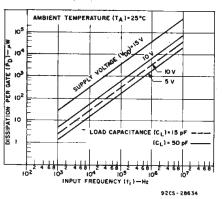


Fig. 14 — Typical dissipation vs. frequency characteristics.

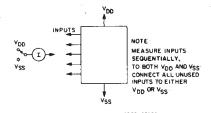


Fig. 15 - Input current test circuit.

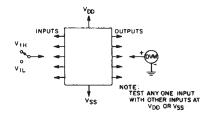


Fig. 16 - Input voltage test circuit.

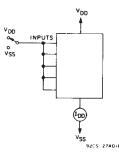
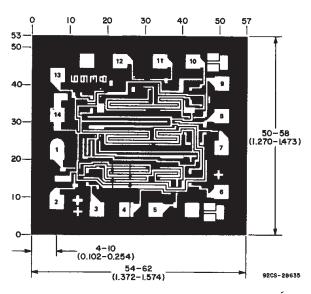


Fig. 17 - Quiescent device current test circuit.



DIMENSIONS AND PAD LAYOUT FOR CD4007UBH

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as Indicated, Grid graduations are in mile (10⁻³ inch).



29-Sep-2011

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD4007UBE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4007UBEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4007UBF	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
CD4007UBF3A	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
CD4007UBM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBM96G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBMG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBMTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



www.ti.com 29-Sep-2011

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD4007UBPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4007UBPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD4007UB. CD4007UB-MIL:

Catalog: CD4007UB



29-Sep-2011

• Military: CD4007UB-MIL

NOTE: Qualified Version Definitions:

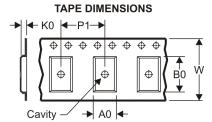
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 20-Aug-2010

TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
		Overall width of the carrier tape
Г	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All ullilerisions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4007UBM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4007UBMT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4007UBNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4007UBPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 20-Aug-2010



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4007UBM96	SOIC	D	14	2500	346.0	346.0	33.0
CD4007UBMT	SOIC	D	14	250	346.0	346.0	33.0
CD4007UBNSR	SO	NS	14	2000	346.0	346.0	33.0
CD4007UBPWR	TSSOP	PW	14	2000	346.0	346.0	29.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

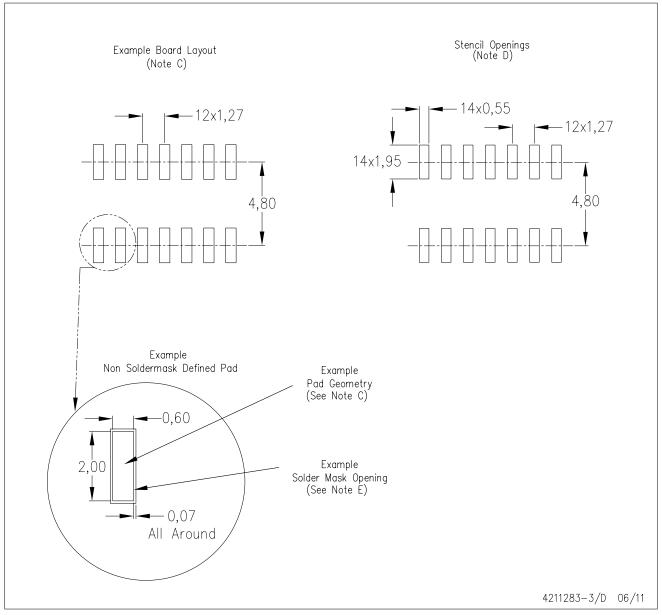


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

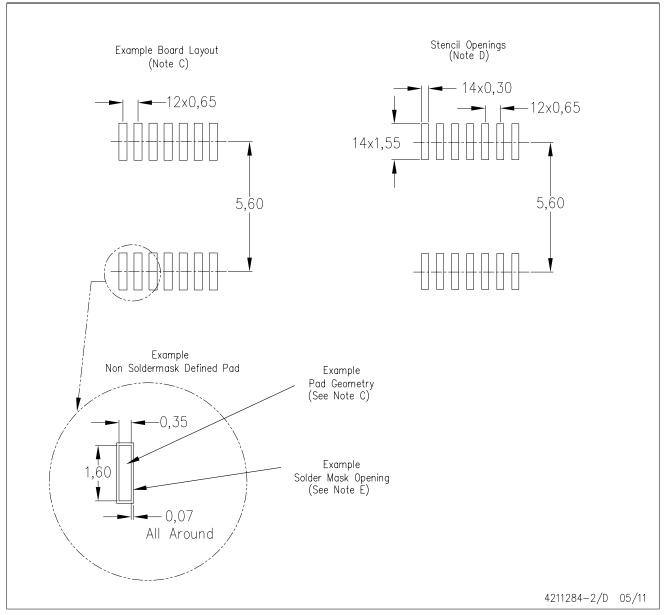


- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Applications

interface.ti.com

Audio www.ti.com/audio Communications and Telecom www.ti.com/communications **Amplifiers** amplifier.ti.com Computers and Peripherals www.ti.com/computers dataconverter.ti.com Consumer Electronics www.ti.com/consumer-apps **Data Converters DLP® Products** www.dlp.com **Energy and Lighting** www.ti.com/energy DSP dsp.ti.com Industrial www.ti.com/industrial Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical

Logic logic.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Security

Power Mgmt power.ti.com Transportation and Automotive www.ti.com/automotive

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID <u>www.ti-rfid.com</u>

OMAP Mobile Processors www.ti.com/omap

Interface

Wireless Connctivity www.ti.com/wirelessconnectivity

TI E2E Community Home Page <u>e2e.ti.com</u>

www.ti.com/security